



IEEE DTDA



2026 IEEE International Conference on Device Technologies for Diversified Applications

Date: Sunday, October 11-Wednesday, October 14, 2026

Venue: Sapporo Grand Hotel & Hokkaido Red Brick Building, Sapporo, Japan

Exhibit and Sponsor Prospectus

DTDA is an international conference fully supported by the IEEE Electron Devices Society (EDS) that focuses on **application-driven** cutting-edge technologies. It was launched in October 2025 in Sendai, bringing together 218 participants from 12 regions. This year's second edition will be held from Sunday, October 11 to Wednesday, October 14, 2026, at the Sapporo Grand Hotel and the Former Hokkaido Government Red Brick Building.

To address diversified applications, DTDA technical sessions are organized by application areas, covering wide range of topics, including MEMS, semiconductor devices, and AI. All technologies are discussed for specific applications, which makes technology visible and emphasized for the applications.

DTDA's mission is to provide an informative and entertaining experience for all attendees. To achieve this, the conference includes exciting, invited speakers and presentations from numerous organization. This year six application areas are scheduled, including Unleashing Power of MEMS, Biosensors/ Bioelectronics/ Biomedical Devices, Robot for Smart Society, Mobility, Environmental Impact Mitigation/Energy Reduction and Water Risk Management, Smart Agriculture on the Ground and in Space. Short courses are scheduled on Sunday, October 11th. We have also set aside time for demo sessions, workshops and other networking events to foster connections and engagement. DTDA is where technology meets application.

Don't miss the opportunity to join us for an unforgettable experience.

Hiro Akinaga/Hokkaido University
General Chair of DTDA2026

DTDA 2026 At-a-glance as of June 5, 2026

	Oct. 10	Day1 Oct. 11				Day2 Oct. 12				Day3 Oct. 13				Day4 Oct. 14							
Room Name	Sapporo Grand Hotel(2F)	Red Brick Bldg Rm A(2F)	Red Brick Bldg Rm B(2F)	Red Brick Bldg Rm A(B1F)	Red Brick Bldg Rm B(B1F)	Sapporo Grand Hotel(2F)	Red Brick Bldg Rm A(2F)	Red Brick Bldg Rm B(2F)	Red Brick Bldg Rm A(B1F)	Red Brick Bldg Rm B(B1F)	Sapporo Grand Hotel(2F)	Red Brick Bldg Rm A(2F)	Red Brick Bldg Rm B(2F)	Red Brick Bldg Rm A(B1F)	Red Brick Bldg Rm B(B1F)	Sapporo Grand Hotel(2F)	Red Brick Bldg Rm A(2F)	Red Brick Bldg Rm B(2F)			
8:30-9:00																					
9:00-9:30																					
9:30-10:00																			Expo-Demo		
10:00-10:30		Setup																	Appl. Session Area 3(3h)		
10:30-11:00																					
11:00-11:30																					
11:30-12:00																					
12:00-12:30																					
12:30-13:00																					
13:00-13:30																					
13:30-14:00	Event IEEE World Technology Summit - Sapporo 2026	Short Course	Expo-Demo				Appl. Session Area 5(3h)	Expo-Demo	Appl. Session Area 1(6h)			Appl. Session Area 4(3h)	Expo-Demo				Appl. Session Area 6(3h)				
14:00-14:30																					
14:30-15:00																					
15:00-15:30										break											
15:30-16:00																					
16:00-16:30																					
16:30-17:00							Appl. Session Area 2(2h)										Closing /Award ceremony				
17:00-17:30																					
17:30-18:00																					
18:00-18:30																					
18:30-19:00		Welcome Reception (18:00-21:00)																			
19:00-19:30																					
19:30-20:00																					
20:00-20:30																					
20:30-21:00																					
							Banquet (19:00~21:00) Venue: Sapporo Grand Hotel Expo-Demo & Poster High Costed Room (Price: T&S)														



Sponsored by: IEEE Electron Devices Society (IEEE EDS)





2026 IEEE International Conference on Device Technologies for Diversified Applications Sponsorship/Exhibition and Benefit

Plan	Fee				
	Platinum Sponsor	Gold Sponsor	Silver Sponsor	Exhibit Only	Refreshment Sponsor
	1,100,000 JPY	550,000 JPY	330,000 JPY	220,000 JPY	330,000 JPY
Luncheon Seminar* *A first-come-first-served basis	✓	✓	✓		
Company logo on the program book	✓	✓	✓	✓	✓
Advertisement of the company in the program book*	A4 Full page	A4 Full page	A4 Full page	A4 Full page	A4 Full page
Company logo on official website E-newsletter screen at session rooms	✓	✓	✓	✓	✓
Company logo featured on the banner at the venue	✓	✓	✓	✓	✓
Exhibit Booth	1 (Complimentary)	1 (Complimentary)	1 (Complimentary)	1	
Number of complementary full conference registration	10	5	3	2	3
Number of complementary short course registration	10	5	3	2	3
Company names awards	✓				
Company name board at refreshment tables					✓

*Ad data due date: September 18, 2026
Ad size: A4 Horizontal 210mm W x 297mm H
Ad data has to be EPS format, PDF/X-1a(font-embedded), or 1-Bit-TIFF.

Exhibition Period

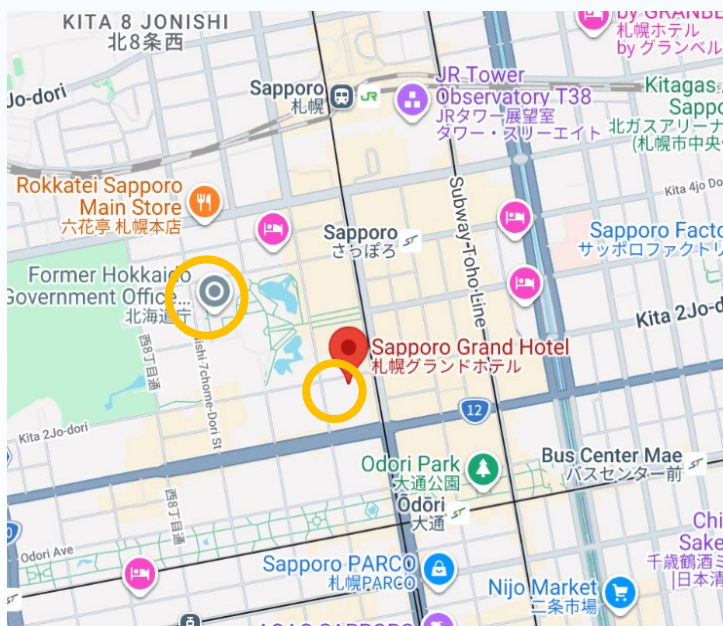
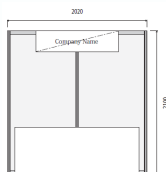
Exhibition Period :
Oct. 11 (Sun) – 14 (Wed), 2026
Sun., October 11 13:00-18:30
Mon., October 12 13:00-18:30
Tue., October 13 13:00-18:30
Wed., October 14 8:30-10:00

Exhibition Venue: Hokkaido Red Brick Building
The exhibitor may want to have a poster panel at the banquet venue on October 12 in addition to the exhibit booth.

Move-in : Monday, October 11 9:00-12:30
Move-out: Wednesday, October 14 16:30-17:30

Exhibit Booth Specification

- Back Panel: W2020 x H2100mm
- Affiliation name board
- Table: W1800 x D600 x H700mm
- Chair: 1
- Table Cloth (White)
- Electricity Supply*: AC Single-phase 100V 50Hz
Upon request



Contact : DTDA 2026 Secretariat

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